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Part Number:

0737800264

Status:

Active

Overview:

HDM Backplane Connector System

Description:

HDM Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 72 Circuits, Mounted Height 14.00mm, Pin Length 4.00mm, Solder Tail

Documents:

3D Model

3D Model (PDF)

Drawing (PDF)

Product Specification PS-73780-999-001 (PDF)

Test Summary TS-73670-990-001 (PDF)

RoHS Certificate of Compliance (PDF)

Agency Certification

UL

E29179

General

Product Family

Series

Application

Comments

Component Type

Overview

Product Name

UPC

Backplane Connectors

73780

Daughtercard, Mezzanine

Solder Tail

PCB Receptacle

HDM Backplane Connector System

HDM

822348168569

Physical

Circuits (Loaded)

Circuits (maximum)

Color - Resin

Durability (mating cycles max)

First Mate / Last Break

Flammability

Guide to Mating Part

Keying to Mating Part

Material - Metal

Material - Plating Mating

Material - Plating Termination

Material - Resin

Net Weight

Number of Columns

Number of Pairs

Number of Rows

Orientation

PC Tail Length

PCB Locator

PCB Retention

PCB Thickness - Recommended

Packaging Type

Pitch - Mating Interface

Pitch - Termination Interface

Plating min - Mating

Plating min - Termination

Polarized to PCB

Stackable

Surface Mount Compatible (SMC)

Temperature Range - Operating

Termination Interface: Style

72

72

Black

250

No

94V-0

No

None

Copper-Nickel-Tin

Gold

Tin

High Temperature Thermoplastic

10.002/g

12

Open Pin Field

6

Vertical

4.00mm

No

None

1.60mm

Tube

2.00mm

2.00mm

0.762µm

2.540µm

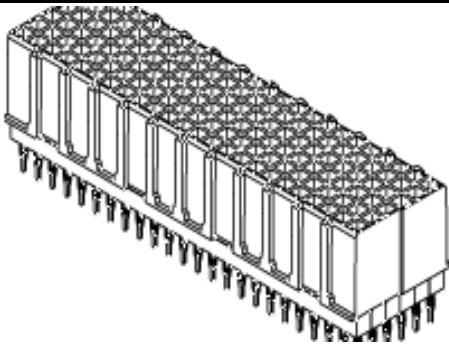
No

Yes

Yes

-55° to +105°C

Through Hole



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

REACH SVHC

Not Contained Per -
D(2020)9139-DC (19
Jan 2021)

Halogen-Free

Status

Low-Halogen

For more information, please visit [Contact US](#)

China ROHS

ELV

RoHS Phthalates

China RoHS

Green Image

Not Relevant

Not Contained

Search Parts in this Series

73780 Series

Mates With

HDM Board-to-Board Backplane Header
[73642](#) , [73643](#) , [73644](#) , [73942](#) , [73943](#) ,
[73944](#) , [74349](#) , [74428](#). HDM Board-to-
Board Stacking Header [73769](#) , [73770](#) ,
[73782](#) , [73783](#) , [73771](#)

Electrical

Current - Maximum per Contact	15.0A, 1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	005
Lead-freeProcess Capability	WAVE
Max. Cycles at Max. Process Temperature	001
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Product Specification	PS-73780-999-001
Sales Drawing	SD-73780-004
Test Summary	TS-73670-990-001

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